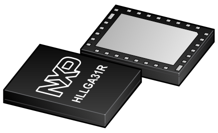


SOT2018-1

HLLGA31, thermal enhanced low profile land grid array package, 31 terminals, 1 mm pitch, 10 mm x 8 mm x 1.365 mm body

2 July 2021 **Package information**

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	HLLGA31
Package style descriptive code	HLLGA (thermal enhanced low profile land grid array)
Mounting method type	S (surface mount)
Issue date	26-03-2019
Manufacturer package code	98ASA01379D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	9.9	10	10.1	mm
package width	7.9	8	8.1	mm
package height	1.295	1.365	1.435	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	31	-	

2 Package outline

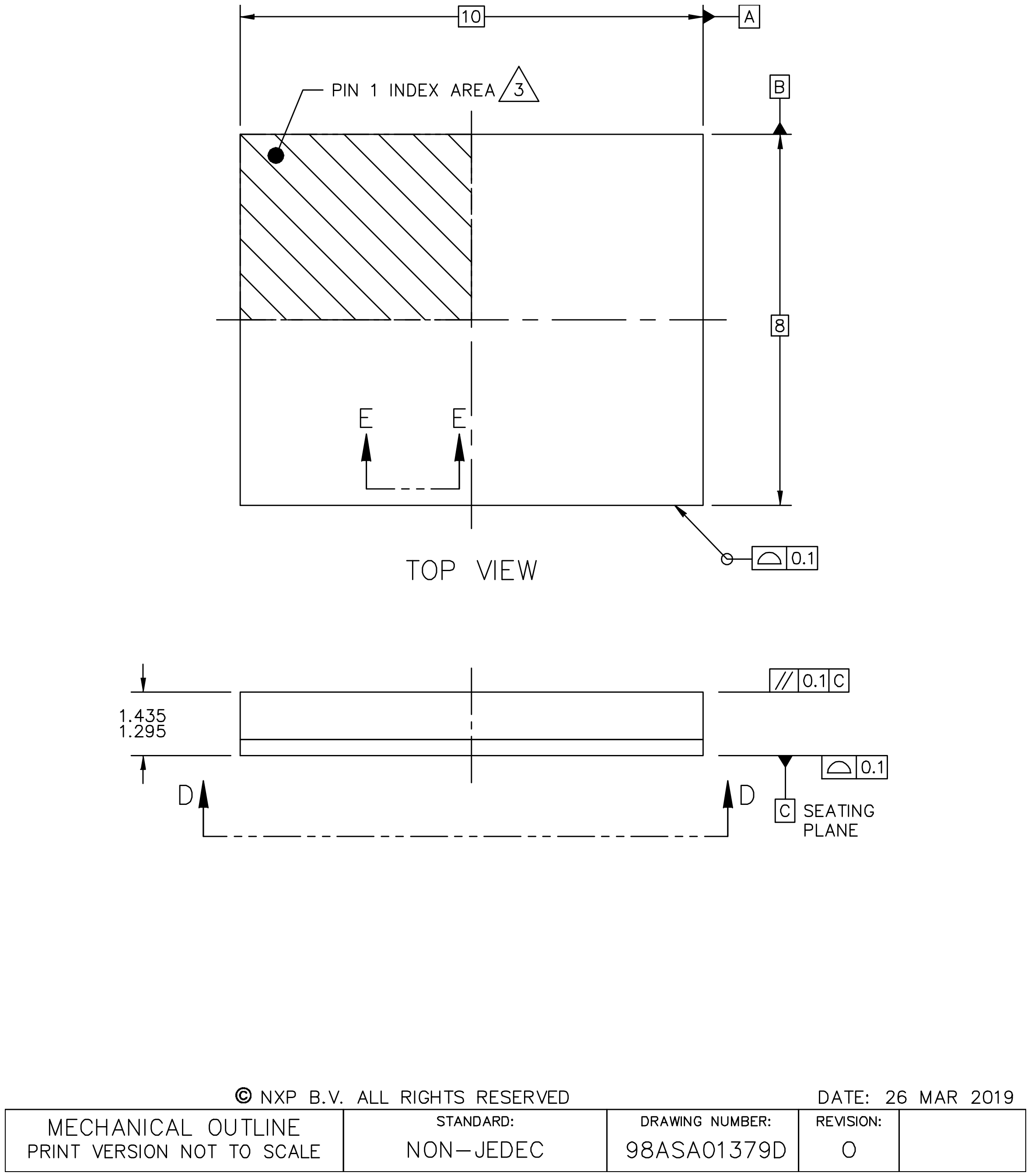


Figure 1. Package outline HLLGA31 (SOT2018-1)

HLLGA31, thermal enhanced low profile land grid array package, 31 terminals, 1 mm pitch, 10 mm x 8 mm x 1.365 mm body

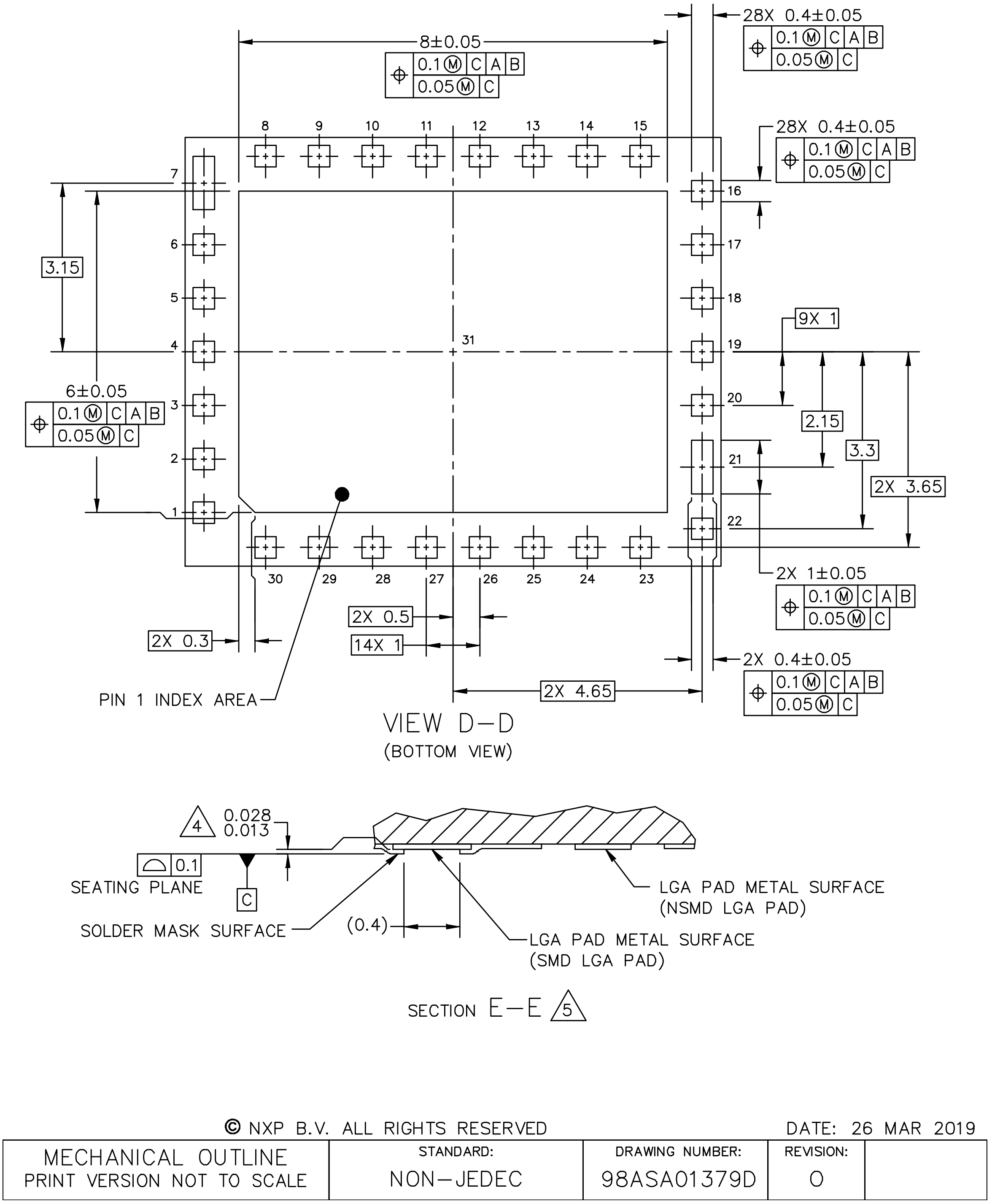
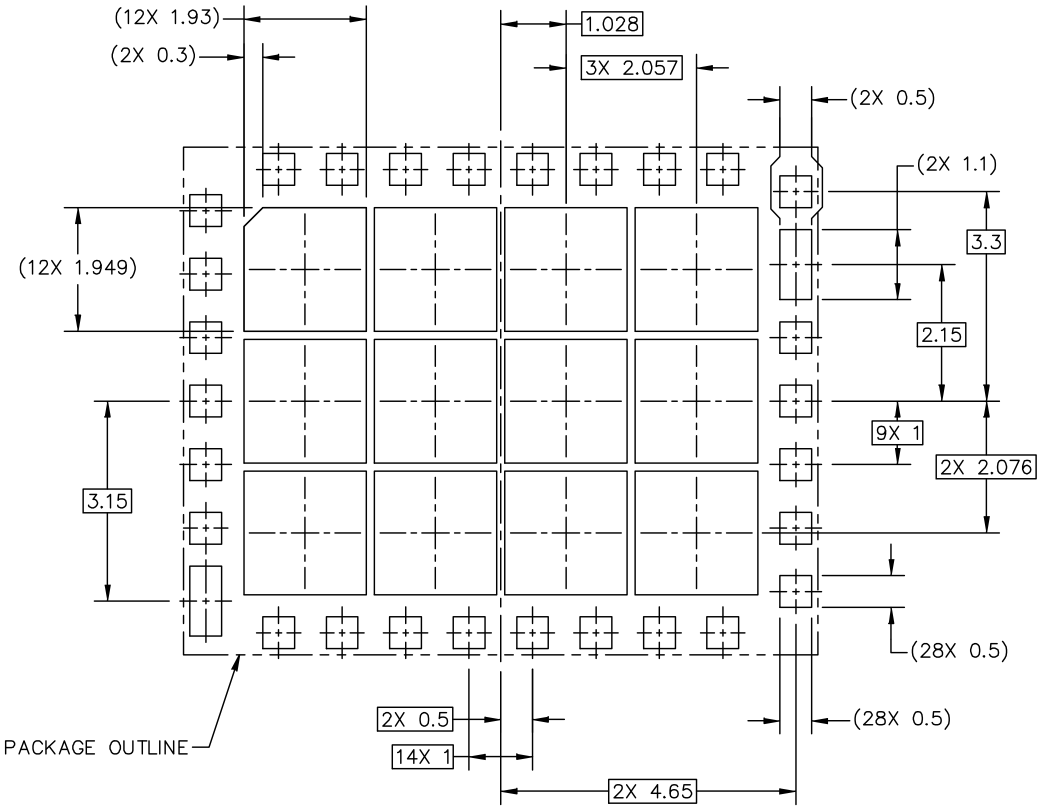


Figure 2. Package outline detail HLLGA31 (SOT2018-1)

3 Soldering



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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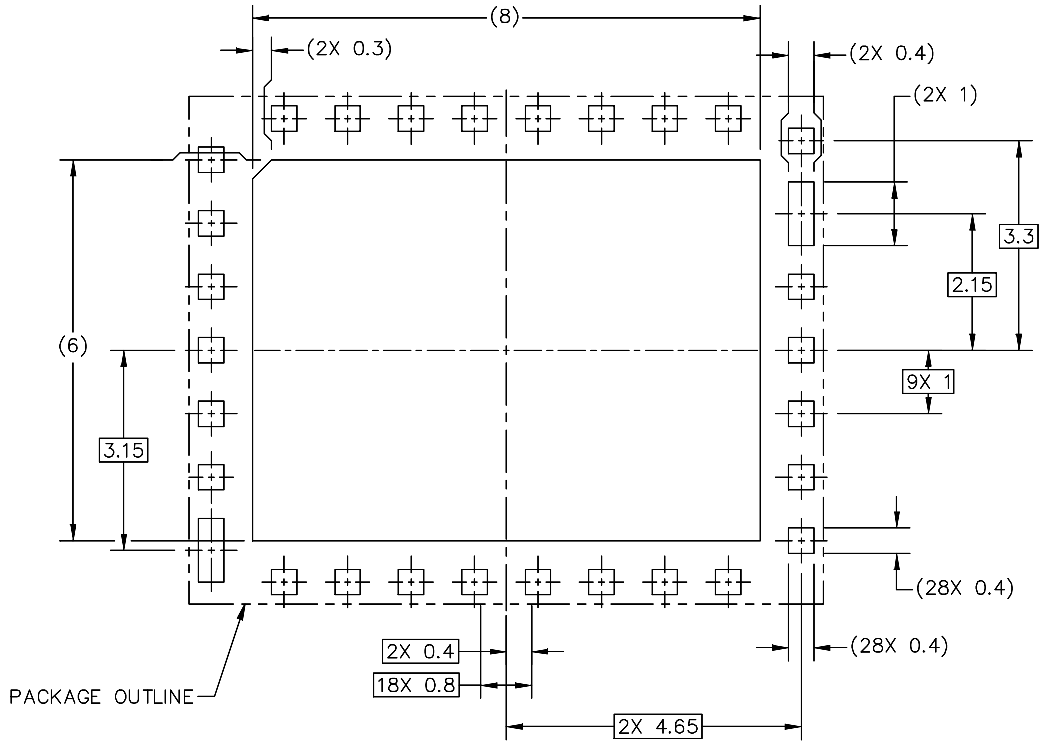
DATE: 26 MAR 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON–JEDEC	DRAWING NUMBER: 98ASA01379D	REVISION: 0	

Figure 3. Reflow soldering footprint part1 for HLLGA31 (SOT2018-1)



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREAS

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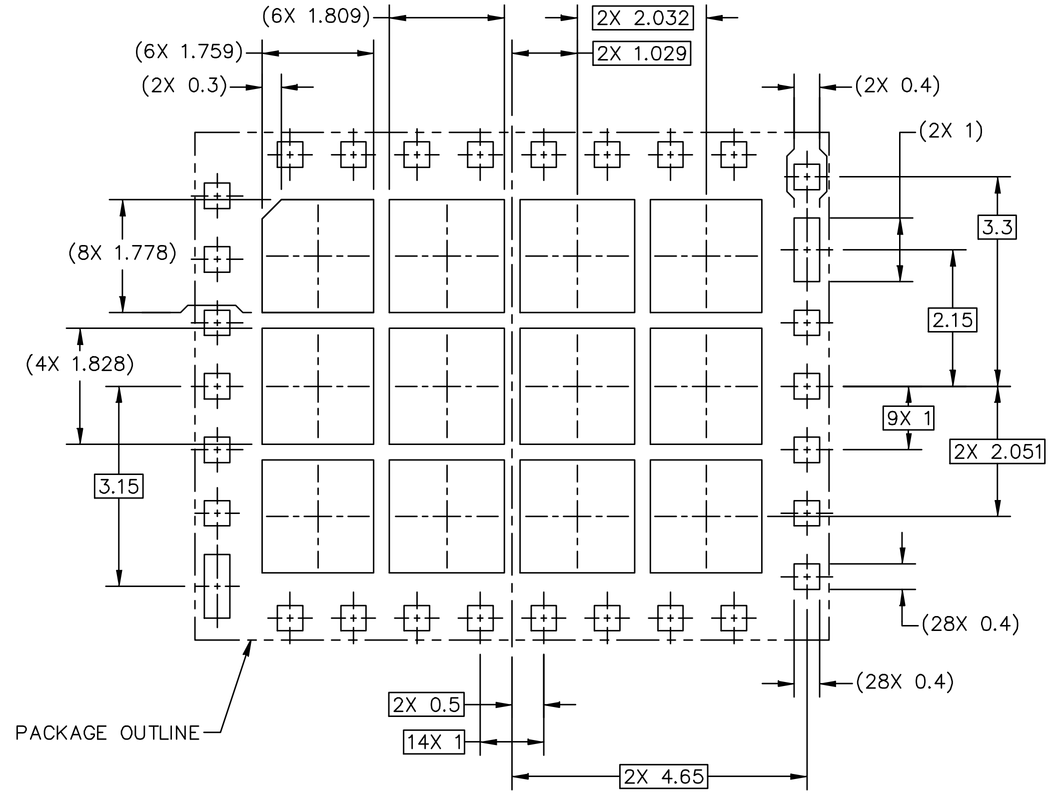
Figure 4. Reflow soldering footprint part2 for HLLGA31 (SOT2018-1)



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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DATE: 26 MAR 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON–JEDEC	DRAWING NUMBER: 98ASA01379D	REVISION: O	

Figure 5. Reflow soldering footprint part3 for HLLGA31 (SOT2018-1)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DIMENSION APPLIES TO ALL LEADS AND FLAG.
5. THE BOTTOM VIEW SHOWS THE SOLDERABLE AREA OF THE PADS. THE CENTER PAD (PIN 31) IS SOLDER MASK DEFINED. SOME PERIPHERAL PADS ARE SOLDER MASK DEFINED (SMD) AND OTHERS ARE NON–SOLDERMASK DEFINED (NSMD).

DATE: 26 MAR 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON–JEDEC	DRAWING NUMBER: 98ASA01379D	REVISION: 0	

Figure 6. Package outline note HLLGA31 (SOT2018-1)

4 Legal information

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